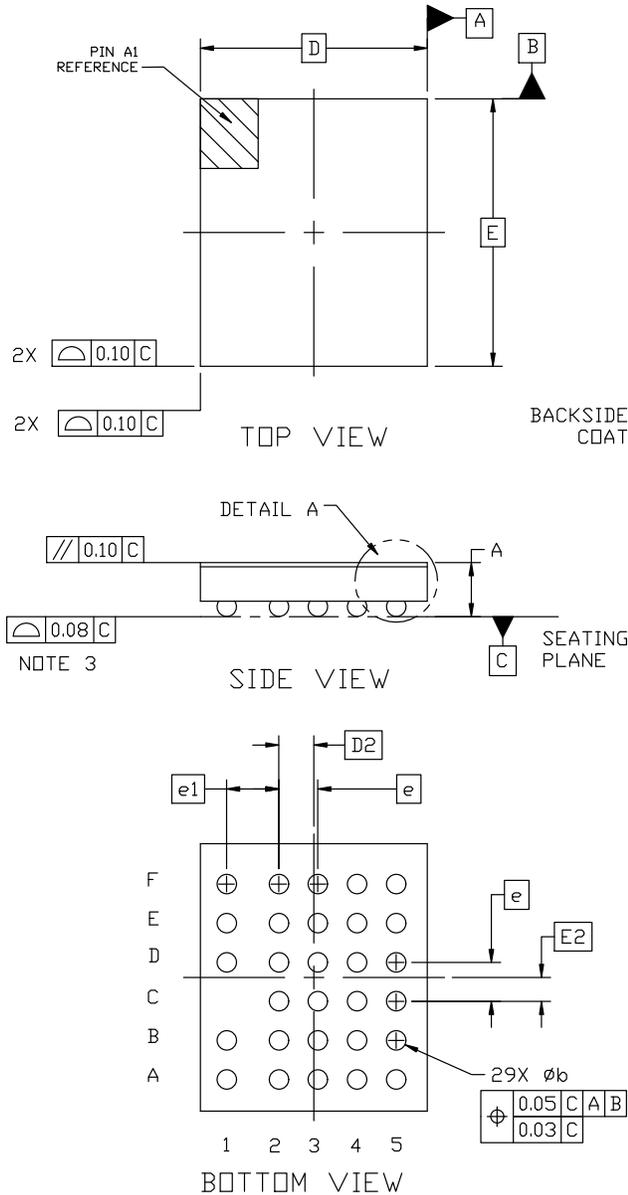




SCALE 4:1

**WLCSP29 2.05x1.74x0.417**  
**CASE 567MK**  
**ISSUE A**

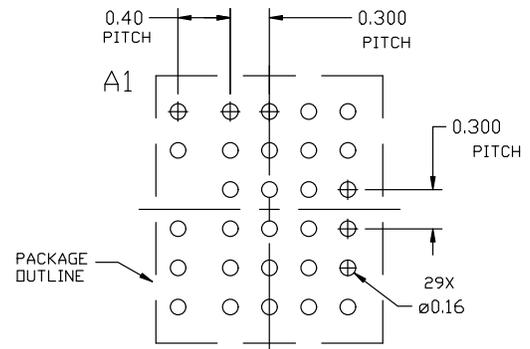
DATE 31 MAY 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION  $b$  IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.369	0.417	0.465
A1	0.103	0.123	0.143
A2	0.229	0.254	0.279
A3	0.037	0.040	0.043
$b$	0.137	0.157	0.177
D	1.740 BSC		
D2	0.270 BSC		
E	2.050 BSC		
E2	0.185 BSC		
$e$	0.300 BSC		
$e1$	0.400 BSC		



RECOMMENDED  
MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

<b>DOCUMENT NUMBER:</b>	<b>98AON05280G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WLCSP29 2.05x1.74x0.417</b>	<b>PAGE 1 OF 1</b>

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.